

TEHCET

Electronics Materials Information



2022 SEMICONDUCTOR INDUSTRY TRENDS AND DRIVERS

Prepared By:

Dan Tracy, Ph.D. and Lita Shon-Roy, MS/MBA

TEHCET CA LLC

11622 El Camino Real #100

San Diego, CA 92130

www.TEHCET.com

info@TEHCET.com

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RESEARCH METHODOLOGY

TEHCET employs subject matter experts having first-hand experience within the industries which they analyze. Most of TEHCET's analysts have over 25 years of direct and relevant experience in their field. Our analysts survey the commercial and technical staff of IC manufacturers and their suppliers, and conduct extensive research of literature and commerce statistics to ascertain the current and future market environment and global supply risks. Combining this data with TEHCET's proprietary, quantitative wafer forecast results in a viable long-term market forecast for a variety of process materials.

READER'S NOTE

This report represents the interpretation and analysis of information generally available to the public or released by responsible agencies or individuals. Data was obtained from sources considered reliable. However, accuracy or completeness is not guaranteed.

ANALYST BIOGRAPHY

Dan Tracy, PhD- Sr. Director of Market Research, TECHCET

Covers silicon wafers, packaging materials, sputtering targets and deposition materials,

Has over 20 years of experience in the electronics industry covering supply-chain topics related to semiconductor packaging, thin films, semiconductor process equipment, and semiconductor materials.

Previously was the senior director of the Industry Research & Statistics group at SEMI.

Worked for Rose Associates covering electronic materials, and for National Semiconductor as a Packaging Engineer.

Holds a Ph.D. in Materials Engineering from Rensselaer Polytechnic Institute.



Dan Tracy, PhD
Sr. Director of Market
Research, TECHCET

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